



## Material Content Data Sheet



Sales Product Name	TLS820B2EL VSE			Issued		16. January 2020		
MA#	MA002805578							
Package	PG-SSOP-14-5			Weight*		82.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.221	1.48	1.48	14763	14763
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		417	
	non noble metal	iron	7439-89-6	0.689	0.83		8331	
	non noble metal	copper	7440-50-8	27.978	33.83	34.71	338263	347115
wire	non noble metal	copper	7440-50-8	0.054	0.06	0.06	647	647
encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1222	
	plastics	epoxy resin	-	4.649	5.62		56208	
	inorganic material	silicondioxide	60676-86-0	45.782	55.35	61.09	553525	610955
leadfinish	non noble metal	tin	7440-31-5	0.976	1.18	1.18	11802	11802
plating	noble metal	silver	7440-22-4	0.768	0.93	0.93	9281	9281
glue	plastics	epoxy resin	-	0.112	0.14		1359	
	noble metal	silver	7440-22-4	0.337	0.41	0.55	4078	5437
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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